

MBR1040CT THRU MBR10200CT

List

List..... 1

Package outline..... 2

Features..... 2

Mechanical data..... 2

Maximum ratings2

Electrical characteristics..... 2

Rating and characteristic curves..... 3

Pinning information.....4

Marking..... 4

Tube packing.....4

Suggested thermal profiles for soldering processes..... 5

High reliability test capabilities.....6

MBR1040CT THRU MBR10200CT

10A High Barrier Power Schottky Rectifiers - 40V-200V

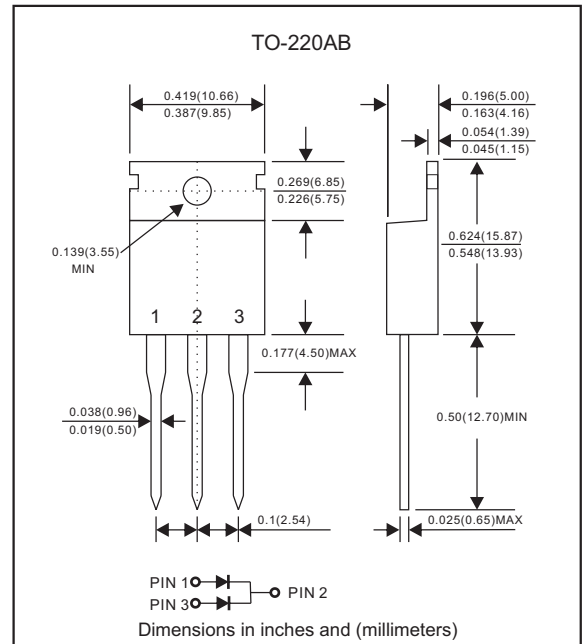
Features

- Low power loss, high efficiency.
- High current capability
- High surge capability.
- Guardring for overvoltage protection.
- Low stored charge majority carrier conduction
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Suffix "-H" indicates Halogen-free part, ex.MBR1040CT-H.

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : JEDEC TO-220AB molded plastic body over passivated chip
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: As marked
- Mounting Position : Any
- Weight : Approximated 2.10 gram

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	MBR 1040CT	MBR 1045CT	MBR 1050CT	MBR 1060CT	MBR 1080CT	MBR 10100CT	MBR 10150CT	MBR 10200CT	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	40	45	50	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	28	31.5	35	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	40	45	50	60	80	100	150	200	V
Maximum average forward rectified current Per device	I_o	10								A
Peak forward surge current 8.3ms single half sine-wave(JEDEC method)	I_{FSM}	125								A
Operating junction temperature range	T_J	-55 to +150						-55 to +175		$^\circ\text{C}$
Storage temperature range	T_{STG}	-65 to +175								$^\circ\text{C}$

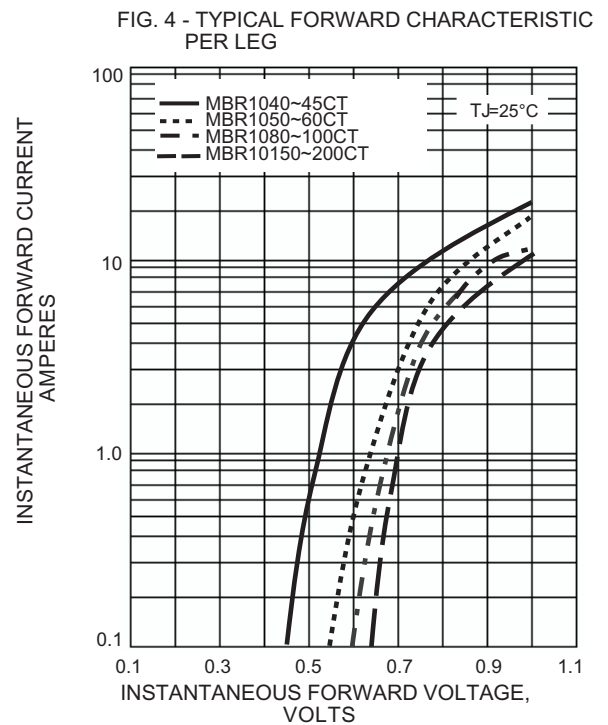
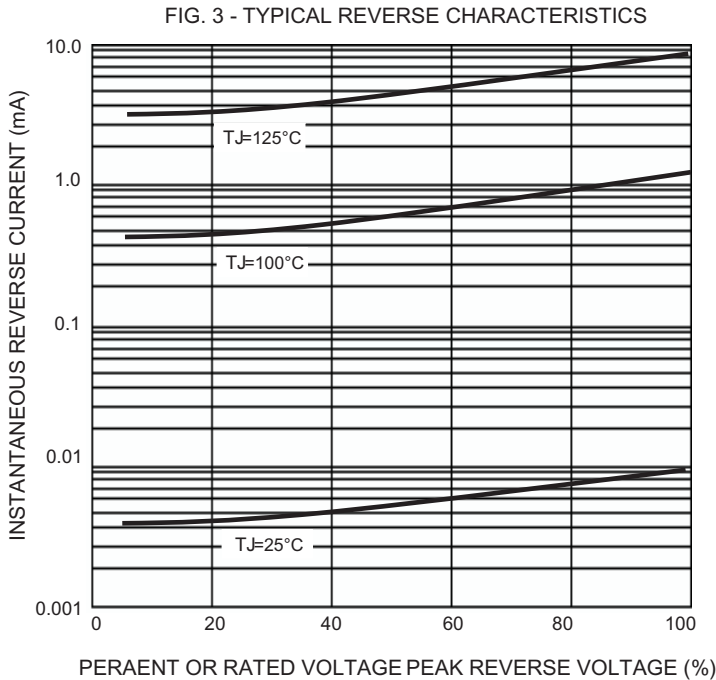
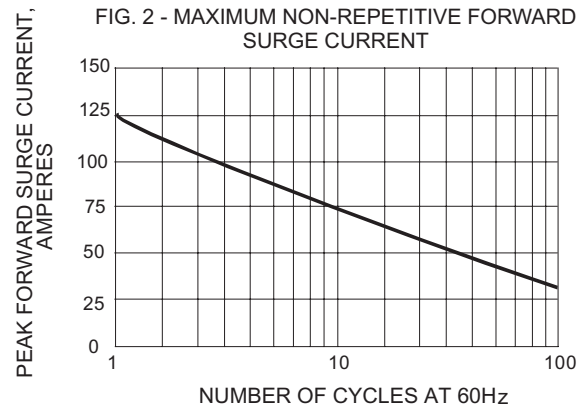
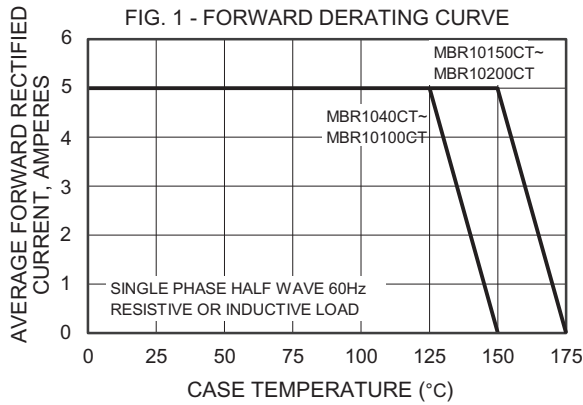
Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	MBR 1040CT	MBR 1045CT	MBR 1050CT	MBR 1060CT	MBR 1080CT	MBR 10100CT	MBR 10150CT	MBR 10200CT	UNIT
Maximum forward voltage at $I_F=5\text{A}$ at $I_F=10\text{A}$	V_F	0.65 0.84		0.75 0.85		0.85 0.95		0.92 1.00		V
Maximum DC reverse current at $T_J=25^\circ\text{C}$ at rated DC blocking voltage at $T_J=125^\circ\text{C}$	I_R	0.05 10			0.01 10				mA mA	

Thermal characteristics

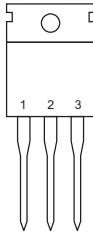
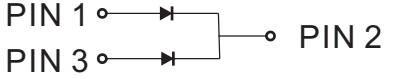
PARAMETER	SYMBOLS	MBR 1040CT	MBR 1045CT	MBR 1050CT	MBR 1060CT	MBR 1080CT	MBR 10100CT	MBR 10150CT	MBR 10200CT	UNIT
Typical thermal resistance junction to case per leg	$R_{\theta JC}$	3.0								$^\circ\text{C}/\text{W}$

Rating and characteristic curves (MBR1040CT THRU MBR10200CT)



MBR1040CT THRU MBR10200CT

Pinning information

Pin	Simplified outline	Symbol
Pin1 anode Pin2 cathode Pin3 anode		

Marking

Type number	Marking code
MBR1040CT	MBR1040CT
MBR1045CT	MBR1045CT
MBR1050CT	MBR1050CT
MBR1060CT	MBR1060CT
MBR1080CT	MBR1080CT
MBR10100CT	MBR10100CT
MBR10150CT	MBR10150CT
MBR10200CT	MBR10200CT

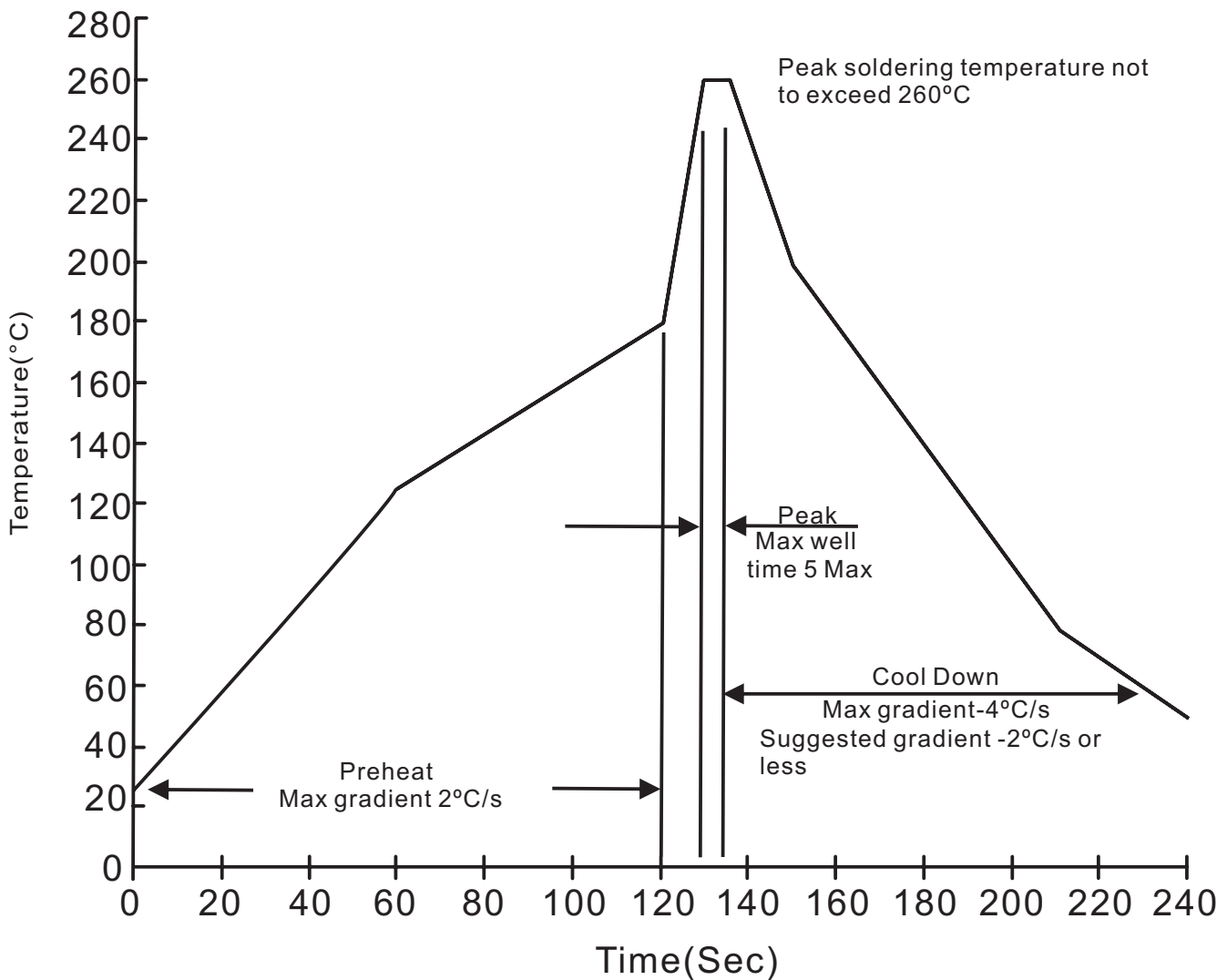
Tube packing

PACKAGE	TUBE (pcs)	TUBE SIZE (m/m)	BOX (pcs)	INNER BOX (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
TO-220AB	50	525*32*7.5	1,000	555*150*40	580*230*175	5,000	15.0

MBR1040CT THRU MBR10200CT

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering



MBR1040CT THRU MBR10200CT**High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at $260\pm 5^{\circ}\text{C}$ for $10\pm 2\text{sec}$. immerse body into solder $1/16''\pm 1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245\pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031